

Surface Mount Standard Recovery

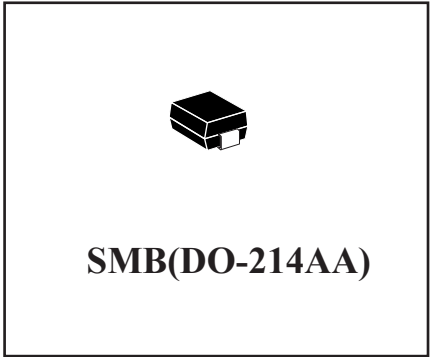
Glass Passivated

(Pb) Lead(Pb)-Free

Features:

- *For Surface Mount Application
- *Glass Passivated Chip
- *Low Reverse Leakage Current
- *Low Forward Voltage Drop And High Current Capability
- *Plastic Material Has UL Flammability Classification 94V-0

**REVERSE VOLTAGE
50 TO 1000 VOLTS
FORWARD CURRENT
2.0 AMPERE**

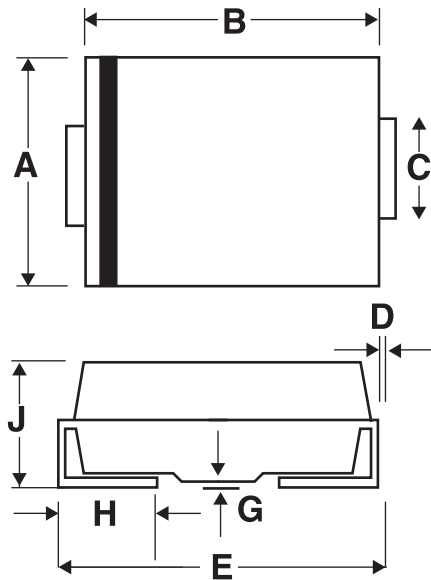


Mechanical Data

- *Case : Molded Plastic
- *Polarity :Indicated by cathode band
- *Weight : 0.003 Ounce ,0.093 grams

SMB Outline Dimensions

Unit:mm



SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.80
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.10	0.20
H	0.76	1.52
J	2.00	2.62

Maximum Ratings and Electrical Characteristics

Rating 25°C Ambient Temperature Unless Otherwise Specified.

Single Phase Half Wave, 60Hz , Resistive or Inductive Load.

For Capacitive Load, Derate Current by 20%.

Characteristics	Symbol	S2A	S2B	S2D	S2G	S2J	S2K	S2M	Unit
Maximum Recurrent Peak Reverse Voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	VRMS	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @TC=100°C	IF(AV)	2.0							A
Peak Forward Surge Current, 8.3 ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	IFSM	50							A
Maximum Instantaneous At 2.0A DC	VF	1.10							V
Maximum DC Reverse Current @Tj=25°C At Rated DC Blocking Voltage @Tj=125°C	IR	5.0 125							uA
Typical Junction Capacitance (Note 1)	C _J	20							P _F
Typical Thermal Resistance (Note 2)	R _{θJL}	25							°C/W
Operating Temperature Range	T _J	-55 to+150							°C
Storage Temperature Range	TSTG	-55 to+150							°C

NOTES: 1.Measured at 1.0MHz applied reverse voltage of 4.0V DC.

2.Thermal Resistance Junction to case.

FIG.1 - FORWARD CURRENT DERATING CURVE

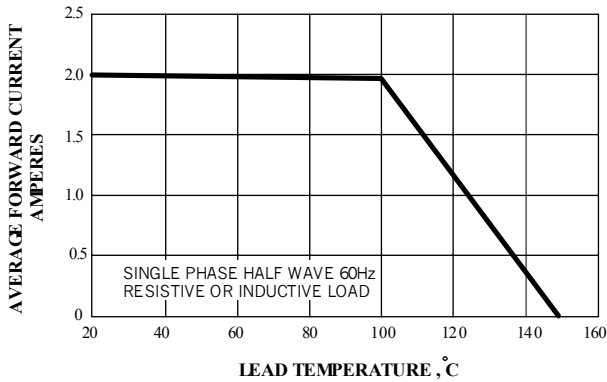


FIG.2 - MAXIMUM NON-REPETITIVE SURGE CURRENT

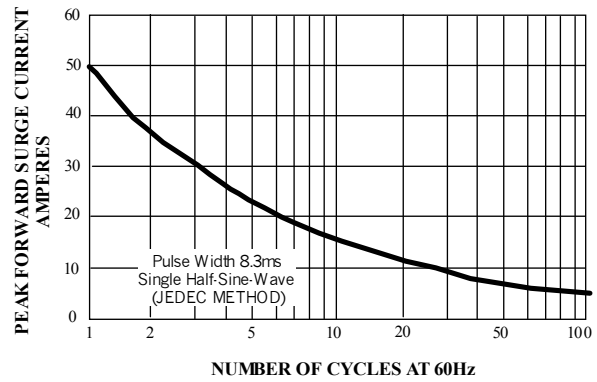


FIG.3 - TYPICAL FORWARD CHARACTERISTICS

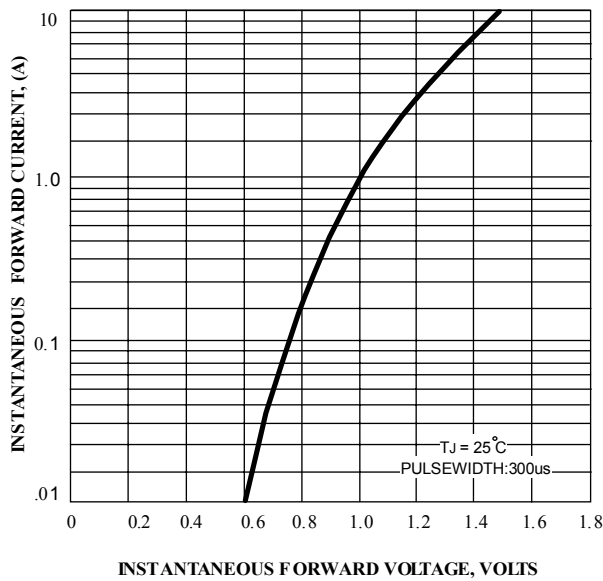


FIG.4 - TYPICAL REVERSE CHARACTERISTICS

